
Electrochemical Processing in ULSI and MEMS 4

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Table of Contents

| | |
|---|-----|
| Preface | iii |
| From Metals to Semiconductors: Challenges in Electrodeposition for Photovoltaic Applications <i>E. Chassaing, J. Guillemoles and D. Lincot</i> | 1 |
| Integration of Vertical Carbon Nanotube Bundles for Interconnects <i>N. Chiodarelli, K. Kellens, D. Cott, N. Peys, K. Arstila, M. Heyns, S. De Gendt, G. Groeseneken and P. M. Vereecken</i> | 11 |
| Interfacial Structure and Chemistry of Potentiodynamically Electrodeposited Ultrathin Pd Films on Pt(111) <i>Y. Park, J. H. Baricuatro, M. A. Hossain and M. P. Soriaga</i> | 25 |
| Understanding, Controlling and Minimizing the Voiding, Sporadically Occurring in Solder Joints with Electroplated Copper <i>F. Wafula, Y. Liu, L. Yin, S. Bliznakov, P. Borgesen, E. Cotts and N. Dimitrov</i> | 43 |
| Electrochemical Properties of Cu Deposition from Methanesulphonate Electrolytes for ULSI and MEMS Applications <i>M. Hasan, D. Casey and J. Rohan</i> | 57 |
| Future Technology Proposal for Damascene Process Using All Wet Electrochemical Technique <i>T. Osaka, M. Yoshino and Y. Shacham-Diamand</i> | 67 |
| Pulsed Aqueous Electrodeposition of Sm-Co Permanent Magnets <i>J. Wei, M. Schwartz and K. Nobe</i> | 75 |
| Nanoscale Topography Measurements with a Metal Nanowire AFM Tip <i>M. Motoyama and F. B. Prinz</i> | 85 |
| Automated Electrodeposition of Bimetallic Noble-Metal Nanoclusters via Redox-Replacement Reactions for Electrocatalysis <i>T. S. Mkwizu, M. Mathe and I. Cukrowski</i> | 97 |
| Author Index | 115 |